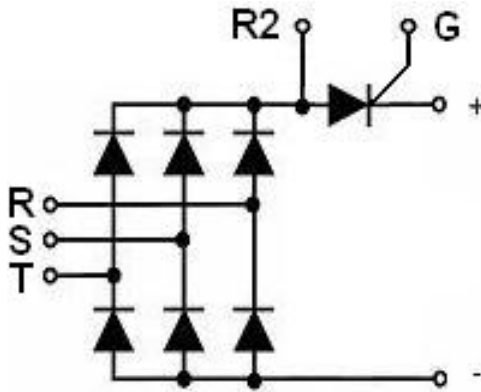


## PRODUCT FEATURES

- Electrically Isolated by DBC Ceramic
- High Surge Current Capability
- Low Inductance Package

## APPLICATIONS

- DC Motor Control and Drives
- Battery Charges ,Heater controls,Light dimmers
- Static switches



## MAXIMUM VOLTAGE RATINGS

$T_C = 25^\circ\text{C}$  unless otherwise specified

Module Type	$V_{RRM}/V_{DRM}$	$V_{RSM}$	Unit
MMK150T160UX6J	1600	1700	V

## ABSOLUTE MAXIMUM RATINGS (Thyristor)

Symbol	Parameter/Test Conditions		Values	Unit
$I_{T(AV)}$	Average On-State Current	Single phase, half wave, 180°conduction, $T_c = 80^\circ\text{C}$	150	A
$I_{T(RMS)}$	R.M.S. On-State Current		225	
$I_{TSM}$	Non-Repetitive Surge On-State Current		3600/3800	
$I^2t$	$I^2t$ (For Fusing)	1/2 cycle, 50/60HZ, peak value, $T_c = 45^\circ\text{C}$	64.8/59.8	KA <sup>2</sup> S
$T_J$	Junction Temperature(Thyristor)		-40 to +125	°C

## ABSOLUTE MAXIMUM RATINGS (Diode)

Symbol	Parameter/Test Conditions		Values	Unit
$I_{F(AV)}$	Average Forward Current	Single phase, half wave, 180°conduction, $T_c = 95^\circ\text{C}$	150	A
$I_{F(RMS)}$	R.M.S. Forward Current		225	
$I_{FSM}$	Non-Repetitive Surge Forward Current		1700/1800	
$I^2t$	For Fusing	1/2 cycle, 50/60HZ, peak value, $T_c = 45^\circ\text{C}$	14.4/13.4	KA <sup>2</sup> S
$T_J$	Junction Temperature(Diode)		-40 to +150	°C

**ELECTRICAL CHARACTERISTICS (Thyristor)**
*T<sub>C</sub>=25°C unless otherwise specified*

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
<b>I<sub>DRM</sub></b>	Maximum Peak Off-State Current	$V_D = V_{DRM}, T_J = 125^\circ\text{C}$			25	mA
<b>I<sub>RRM</sub></b>	Maximum Peak Reverse Current	$V_R = V_{RRM}, T_J = 125^\circ\text{C}$			25	
<b>V<sub>TM</sub></b>	Maximum on-state voltage drop	$I_{TM}=150\text{A}, t_d=10\text{ ms, half sine}$			1.18	V
<b>V<sub>TO</sub></b>	For power-loss calculations only	$T_J = 125^\circ\text{C}$			0.9	V
<b>r<sub>T</sub></b>					2.0	mΩ
<b>V<sub>GT</sub></b>	Max. required DC gate voltage to trigger	$V_A=6\text{V}, R_A=1\Omega, T_J = -40^\circ\text{C}$			4.0	V
		$V_A=6\text{V}, R_A=1\Omega$		0.8	2.5	
		$V_A=6\text{V}, R_A=1\Omega, T_J = 125^\circ\text{C}$			1.7	
<b>I<sub>GT</sub></b>	Max. required DC gate current to trigger	$V_A=6\text{V}, R_A=1\Omega, T_J = -40^\circ\text{C}$			270	mA
		$V_A=6\text{V}, R_A=1\Omega$		65	150	
		$V_A=6\text{V}, R_A=1\Omega, T_J = 125^\circ\text{C}$			80	
<b>V<sub>GD</sub></b>	Max. required DC gate voltage not to trigger,	$V_D = V_{DRM}, T_J = 125^\circ\text{C}$			0.25	V
<b>I<sub>GD</sub></b>	Max. required DC gate current not to trigger,	$V_D = V_{DRM}, T_J = 125^\circ\text{C}$			6	mA
<b>I<sub>H</sub></b>	Maximum holding current			200	400	mA
<b>I<sub>L</sub></b>	Maximum latching current			250	500	mA
<b>P<sub>GM</sub></b>	Maximum peak gate power				12	W
<b>P<sub>G(AV)</sub></b>	Maximum average gate power				3.0	
<b>I<sub>GM</sub></b>	Maximum peak gate current				3.0	A
<b>-V<sub>GM</sub></b>	Maximum peak negative gate voltage				10	V
<b>dv/dt</b>	Critical Rate of Rise of Off-State Voltage, $T_J=125^\circ\text{C}$ , exponential to 67% rated $V_{DRM}$				1000	V/μs
<b>di/dt</b>	Max. Rate of Rise of Turned-on Current, $T_J = 125^\circ\text{C}, I_{TM}=500\text{A}$ , rated $V_{DRM}$				150	A/μs

**ELECTRICAL CHARACTERISTICS (Diode)**

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
<b>I<sub>RM</sub></b>	Maximum Reverse Leakage Current	$V_R = V_{RRM}$			0.5	mA
		$V_R = V_{RRM}, T_J = 125^\circ\text{C}$			10	
<b>V<sub>F</sub></b>	Forward Voltage Drop	$I_F=150\text{A}$			1.25	V
<b>V<sub>TO</sub></b>	For power-loss calculations only, $T_J = 125^\circ\text{C}$				0.9	V
<b>r<sub>T</sub></b>					2.2	mΩ

**MODULE CHARACTERISTICS**
*T<sub>C</sub>=25°C unless otherwise specified*

<b>T<sub>STG</sub></b>	Storage Temperature Range		-40 to +125	°C
<b>V<sub>ISO</sub></b>	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
<b>Torque</b>	to heatsink	Recommended (M6)	3~5	N.m
<b>Torque</b>	to terminal	Recommended (M6)	3~5	N.m
<b>R<sub>th(J-C)</sub></b>	Junction-to-Case Thermal Resistance(Per Thyristor/Per Diode)		0.18/0.45	K/W
<b>Weight</b>			330	g

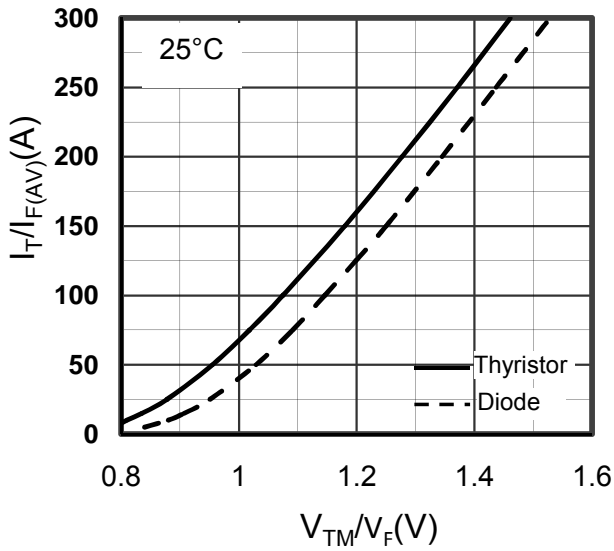


Figure1. Forward Voltage Drop vs Forward Current

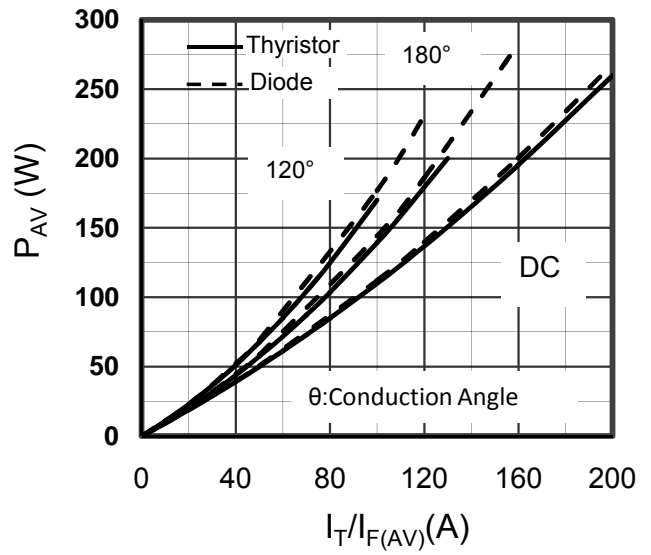


Figure2. Power dissipation vs.  $I_T/I_{F(AV)}$

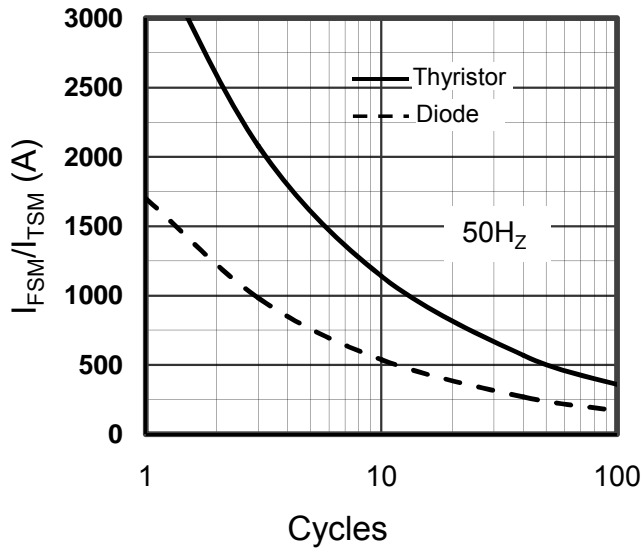


Figure3. Diode and SCR Max Non-Repetitive Surge

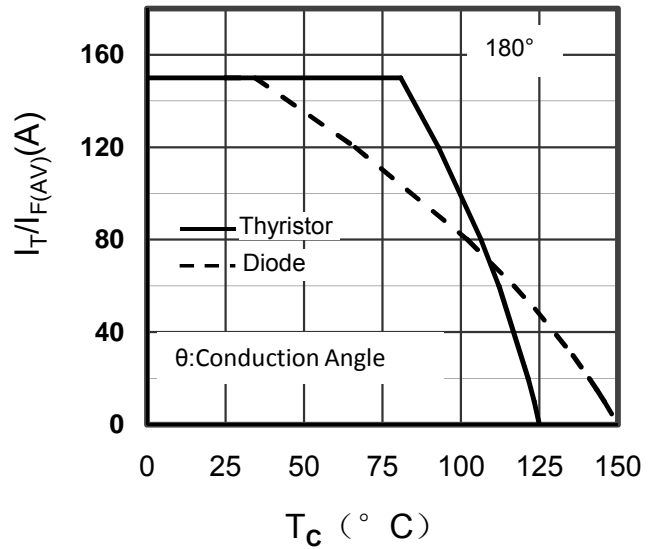


Figure4. Diode  $I_{F(AV)}$  and SCR  $I_{T(AV)}$  vs.  $T_C$

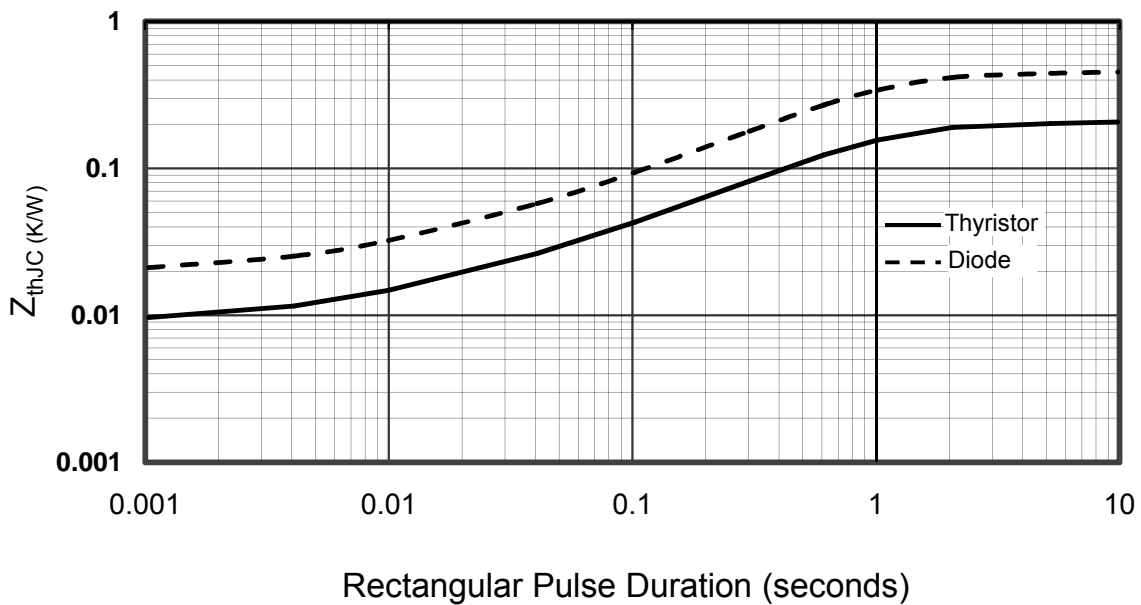


Figure5. Transient Thermal Impedance of Diode and SCR

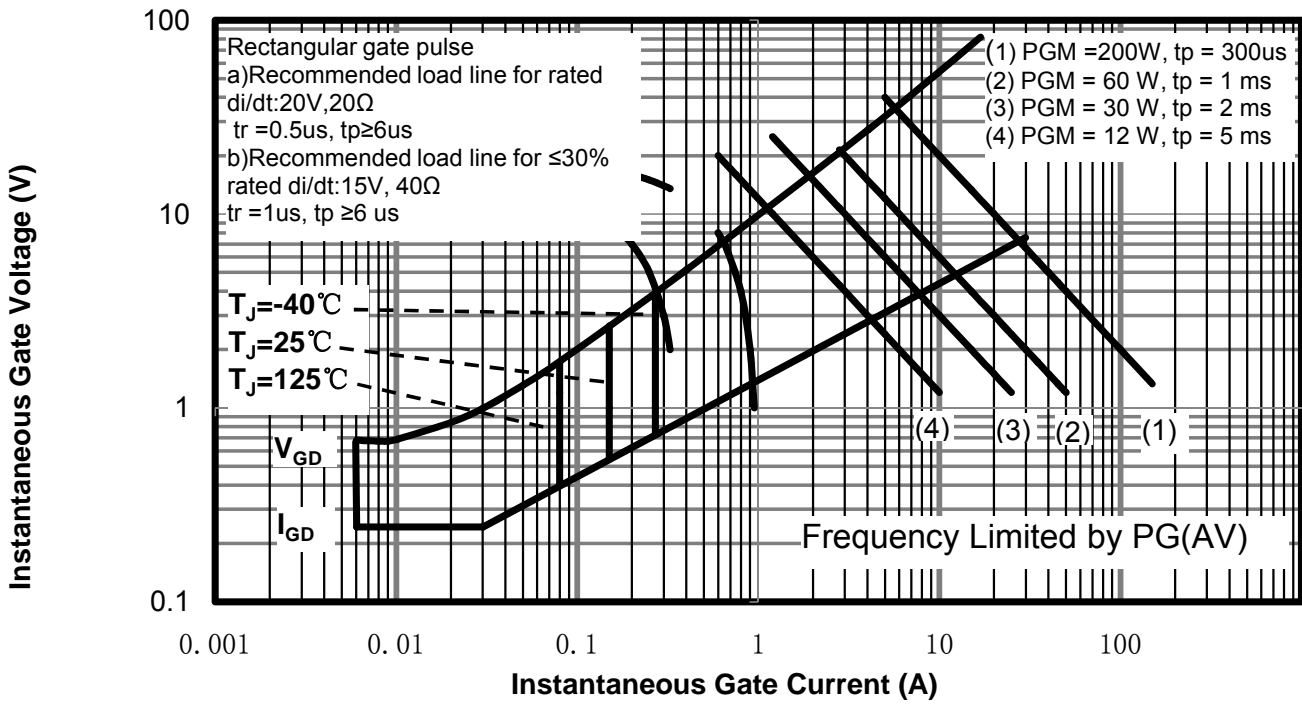
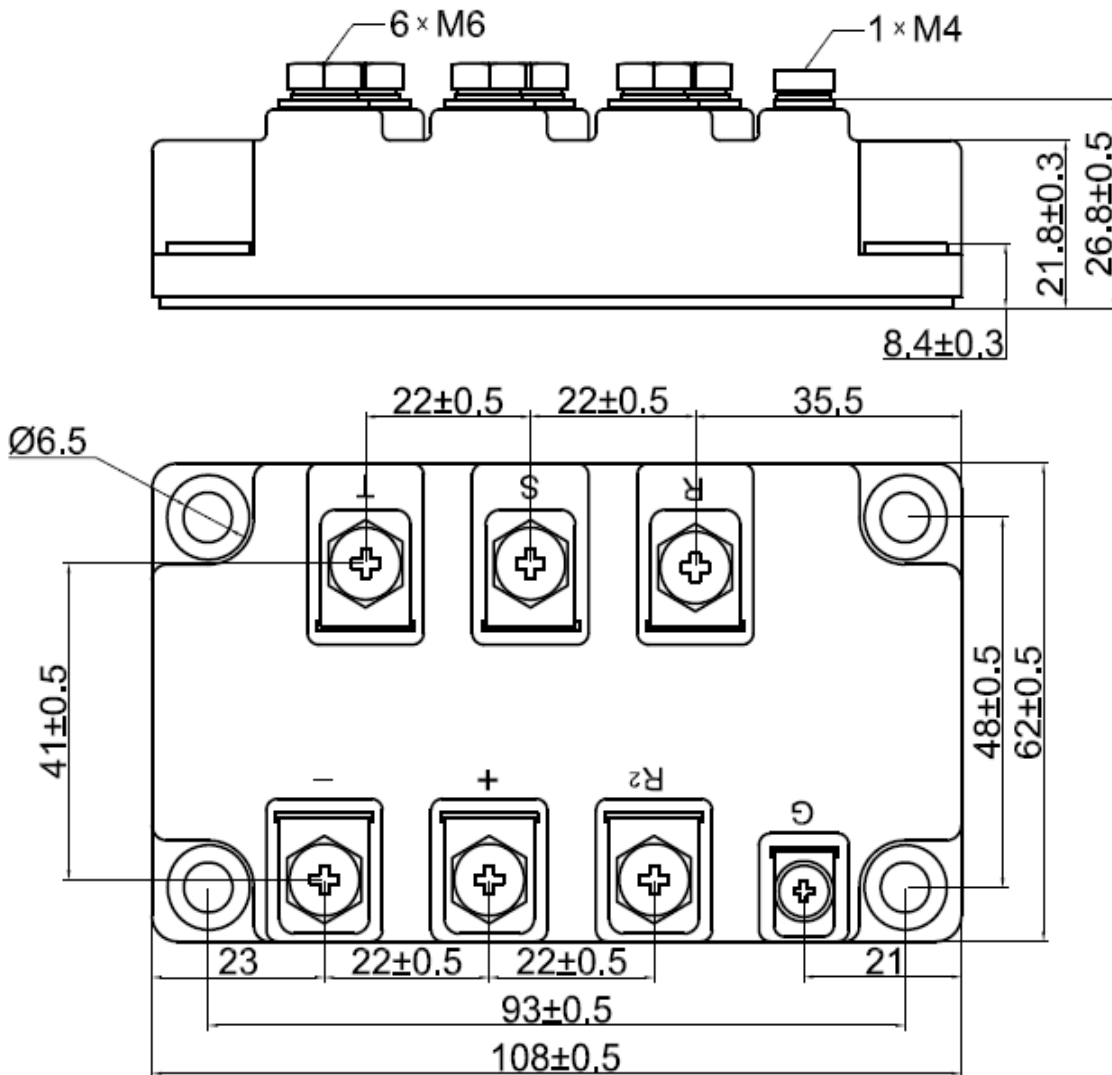


Figure 6. SCR Gate Characteristics



Dimensions in Millimeters  
 Figure 7. Package Outline